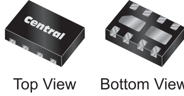
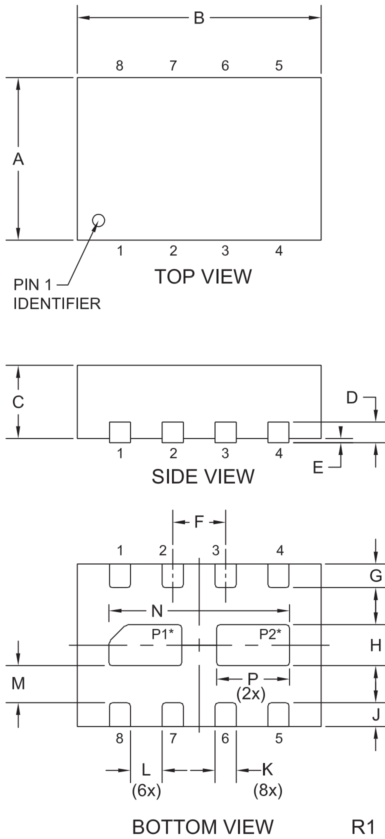
Package Details
TLM832DS Case



Mechanical Drawing



* Exposed pad P1 common to pins 7 and 8
Exposed pad P2 common to pins 5 and 6

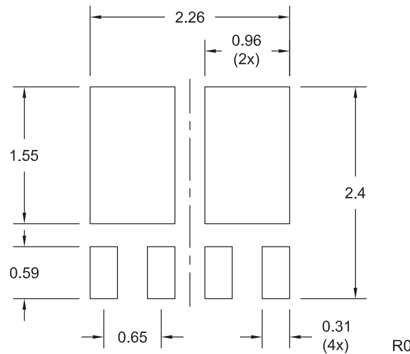
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.077	0.081	1.95	2.05
B	0.116	0.120	2.95	3.05
C	0.031	0.039	0.80	1.00
D	0.006	0.010	0.16	0.25
E	0.000	0.002	0.00	0.05
F	0.026		0.65	
G	0.008	0.016	0.19	0.40
H	0.014	0.024	0.35	0.61
J	0.008	0.016	0.19	0.40
K	0.008	0.012	0.21	0.31
L	0.013	0.017	0.34	0.44
M	0.006	--	0.15	--
N	0.087		2.22	
P	0.029	0.039	0.74	1.00

TLM832DS (REV:R1)

Part Marking:
2-3 Character Alpha/Numeric Code

Lead Code:
Reference individual device datasheet.

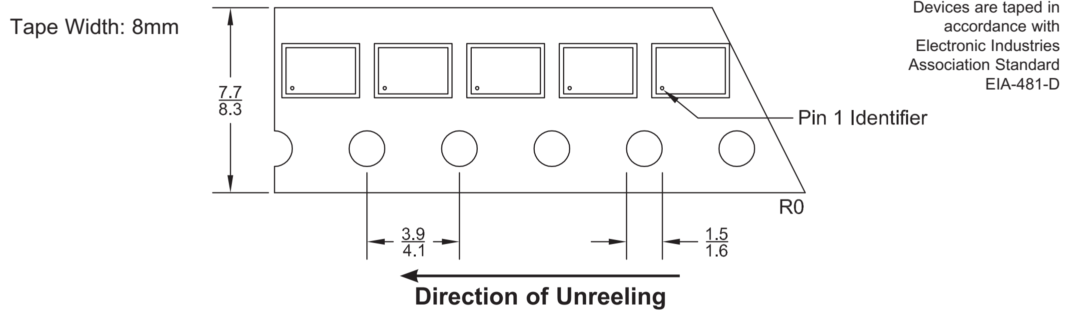
Mounting Pad Geometry
(Dimensions in mm)



R0 (7-February 2012)

Package Details
TLM832DS Case

Tape Dimensions and Orientation (Dimensions in mm)



Packaging Base

7" Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

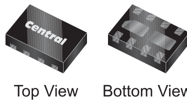
Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7"	9	27,000	9x9x5	23x23x13	4	2
	17	51,000	9x9x9	23x23x23	7	4
	40	120,000	21x9x9	53x23x23	14	7
	108	324,000	27x9x17	69x23x43	39	18

Ordering Information

- For devices taped and reeled on 7" reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

Material Composition Specification

TLM832DS Case



Top View Bottom View

Device average mass . . . . 13.1 mg

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.29%	0.3	Si	7440-21-3	2.29%	0.3	22,901
bond wire	gold	0.46%	0.06	Au	7440-57-5	0.46%	0.06	4,580
leadframe	Cu alloy w/ silver plating	18.24%	2.39	Cu	7440-50-8	17.63%	2.31	176,336
				Fe	7439-89-6	0.4%	0.053	4,046
				Zn	7440-66-6	0.02%	0.003	229
				Ag	7440-22-4	.18%	0.023	1,756
die attach	silver epoxy	0.58%	0.076	epoxy resin	Proprietary	0.11%	0.015	1,145
				Ag	7440-22-4	0.47%	0.061	4,656
encapsulation*	EMC GREEN	77.97%	10.215	silica (fused)	60676-86-0	73.05%	9.57	730,534
				epoxy resin	29690-82-2	2.34%	0.307	23,435
				phenol resin	9003-35-4	2.34%	0.307	23,435
				carbon black	1333-86-4	0.24%	0.031	2,366
plating	matte tin	0.46%	0.06	Sn	7440-31-5	0.46%	0.06	4,580

*EMC GREEN molding compound is Halogen Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (11-January 2012)